

NALCO - Polishing Slurries for Silicon**NALCO™2350**

Nalco 2350 is a colloidal silica polishing slurry specifically formulated for applications where high removal rate is the key parameter for the stock polish step. Nalco 2350 is one of the most widely used silicon polishing slurries in the world. Nalco 2350 yields exceptional surface quality.

NALCO™2354

Nalco 2354 is a colloidal silica polishing slurry specifically formulated for the polishing of silicon wafers. Nalco 2354 has a higher removal rate than Nalco 2350. This product is used primarily for stock removal for maximum removal rates and may also be used in final wafer polishing with adjustments in operation conditions.

NALCO™2360

Nalco 2360 is a colloidal silica polishing slurry specifically formulated for the polishing of silicon wafers. It is an aqueous solution of discrete, submicron silica particles and is formulated for polishing performance and efficiency.

Nalco 2360 offers:

- ⇒ Good surface finish
- ⇒ Applicability as a stock or a final polish slurry for silicon
- ⇒ Wide variety of applications
- ⇒ Assurance of high quality and consistency
- ⇒ Economy of a high solid product

Property Comparison

Typical Properties	NALCO™2350	NALCO™2354	NALCO™2360
Particle Diameter, nm	50 - 70	50 - 70	60
Specific Gravity	1.38	1.35-1.38	1.38
Viscosity @ 25° C.	10.0	25.0	10.0
Percent Sodium	0.4	0.4	0.4
Avg. pH @ 25° C.	11	12	8.5
Percent Silica	50	46	50

Precautionary Notes and Disposal

Follow all MSDS and label precautions and good industrial safety and hygiene practices when handling or using this product. Keep this and all industrial materials away from untrained personnel. Dispose in accordance with applicable regulations.

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